



Product Change Notification

Change Notification #: 813836-01

Change Title: MINOR CHANGE,
Update to Intel Standard Labels & Customer
Custom Specific Labels
PCN 813836-01, Transport Media, Label,
Removing reference to *Country of Origin* and adding
new values *Manufactured In* and *Final Assembly* to
various labels used in the shipment of products
Reason for Revision: Refreshed list of possible SKUs
impacted and added information and disclaimers of
change

Date of Publication: April 15, 2024

Key Characteristics of the Change:

Transport Media, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	August 11, 2023
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Description of Change to the Customer:

Reason for Revision: Refreshed list of possible SKUs impacted and added information and disclaimers of change

Note: PCN813836-01 is a revision of prior published PCN119635-00. Typically, the revised PCN number would have been PCN119635-01. However, due to PCN transition from Quality Document Management System (QDMS) to the Research & Documentation Center (RDC), the change notification was assigned a different PCN number. Customers may find the original PCN119635-00 attached (if viewed using a PDF viewer).

Major updates to the original PCN are displayed in blue font.

Starting August 2023, Intel began implementing a system change for all labels placed on boxes or bags used in the shipment of products. For labels that are in scope, Customers will no longer see a reference to the *Country of Origin (COO)*, *Assembled In*, *Made In* or *Made In [Country] with foreign components*. Instead, Intel will now display two new values entitled, “*Manufactured In*” and “*Final Assembly*” with their accompanying value(s).

The term *Manufactured In* will represent the Country of Fabrication (COF), while the term *Final Assembly* will represent the Country of Final Assembly (COA). Barcoded values (where applicable) will depend upon the location and product. Please see the chart below.

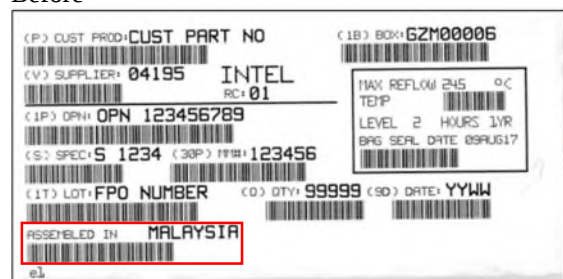
Label Header	Interpretation of Value Displayed
Manufactured In	The country of Fabrication (COF)
Final Assembly	The country of Final Assembly (COA)
Barcoded Field (if applicable)	Contains the Country of Origin (COO)* *COO = COF if shipping to Japan, or if shipping a monolithic product to US *COO = COA if shipping to regions except Japan or shipping non-monolithic products to US

Additionally, wherever the name of a country is spelled out on a label, going forward it will now be abbreviated using a two-digit country code to represent the country. If more than one country was involved in the Fabrication or Final Assembly, customers will see multiple abbreviated country code values in the displayed area on the label.

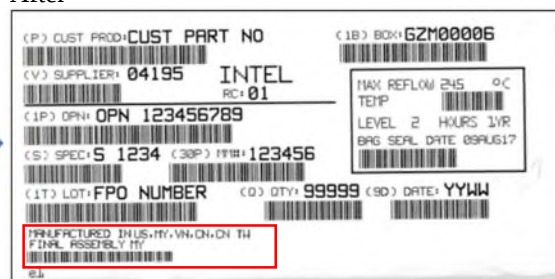
Please be aware that all pictures shared herein are for example purposes only. Each picture represents a change being applied broadly to hundreds of labels. Therefore, rather than list every possible customization possible, the examples can be adapted to labels placed on boxes or bags used to ship products.

Examples of Changes Made to the Standard Intermediate Box

Before

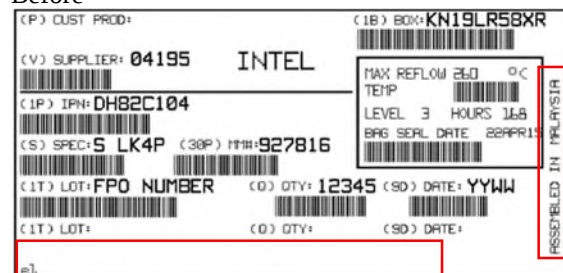


After

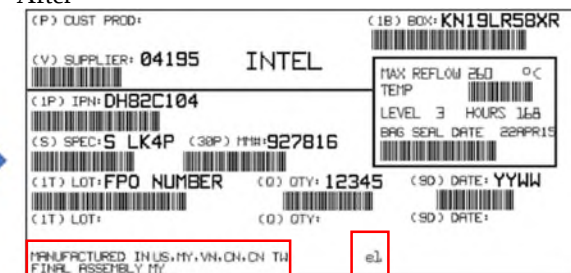


Note: Barcode contains the Country of Origin (COO) value. See interpretation table above.

Before



After



Note: In cases where the Pb-free indicator (i.e., “e1”) is printed on a label, it may shift to the right or print lower on the label, making room to display the Manufactured In (COF) values and/or the Final Assembly (COA) values.

Example of a Customer Specific Intermediate Box Label

(P) CUST PROD:	(1B) BOX: KN19LR58XR
(V) SUPPLIER: 04195	CUST NAME
(1P) IPN: DH82C104	MAX REFLOW 260 °C
(S) SPEC: S LK4P (30P) HWH: 927816	TEMP
(1T) LOT: FPO NUMBER	LEVEL 3 HOURS 168
(O) QTY: 12345	BAG SEAL DATE 22APR15
(SD) DATE: YYWW	
(1T) LOT:	(O) QTY:
(SD) DATE:	
MANUFACTURED IN US,MY,VN,CN,CN TW	
FINAL ASSEMBLY MY	

Note: If customers have a unique label showing their customer name in the label, the word “Intel” would be replaced with the customer’s name.

Example of a Standard Die I-Box

Before

(P) CUST PROD:	(1B) BOX: RLP00003
(V) SUPPLIER: 04195	INTEL
(1P) IPN: INTEL PRODUCT NAMEXX	
(S) SPEC: S 1234 (30P) HWH: 123456	
(1T) LOT: FAB NUMBER1	(O) QTY: 123456 (SD) DATE:
MADE IN MALAYSIA with foreign component	

After

(P) CUST PROD:	(1B) BOX: RLP00003
(V) SUPPLIER: 04195	INTEL
(1P) IPN: INTEL PRODUCT NAMEXX	
(S) SPEC: S 1234 (30P) HWH: 123456	
(1T) LOT: FAB NUMBER1	(O) QTY: 123456 (SD) DATE:
MANUFACTURED IN US,MY,VN,CN,CN TW	

Note: if the words, Made In [Country] with foreign component are on a label, it is replaced by “Manufactured In”.

Example of a Custom Shipping Label

Before

(K) Cust. PO: PO NUMBER
(P) Cust. Part: CUST PART NO
(1P) HWH Part: INTEL PROD NO
(1K) Packing Slip: DN NUMBER
(O) Quantity: 12345
(SD) Date Code: 1515 (4L) COO: MY
(1T) Lot Code: FPO NUMBER
(ED) Ship Date: 04/05/15

After

(K) Cust. PO: PO NUMBER	
(P) Cust. Part: CUST PART NUMBER	
(1P) HWH Part: INTEL PROD NO	
(1K) Packing Slip: DN NUMBER	
(O) Quantity: 12345 (SD) Date Code: 1515	
Manufactured in US,MY,VN,CN,CN TW	
Final Assembly MY	
(1T) Lot Code: FPO NUMBER	
(ED) Ship Date: MM/DD/YYYY	

Note: The Date Code field moves, and the COO header is replaced by the header name Manufactured In and Final Assembly Fields.

Customer Impact of Change and Recommended Action:

Intel considers this a Minor Change. This change pertains only to labels used in the shipment of products and not to the actual products themselves. There is no change to the form, fit, functionality, quality or reliability for the products.

This change is NOT product specific and is being communicated very broadly. Not all customers receiving this PCN will be impacted by the particular label changes. For those receiving this notification it indicates only that their products *may* be impacted, but *not guaranteed* to be impacted.

Customers should expect to see a mixture of shipments using older labels and newly changed labels until the older label stock inventory is fully depleted. Any existing label stock/materials already labeled, packed and stored as warehouse inventory will not be relabeled before shipping to customers.

This change is not expected to be a quick change. The process started August 2023 and is anticipated to take several quarters to implement across all impacted labels impacted by the scope.

Customers should notify your inbound shipment & receiving departments to expect and anticipate these label changes.

Distributors should forward this communication to their customers accordingly.

Please contact your appropriate Intel Account Representative with any questions or concerns regarding the changes communicated in this updated Product Change Notification.

Products Affected/Intel Ordering Codes:

Please reference the attached excel file using a PDF-viewer.

Note: The label changes referenced in this notification are not product-specific. Therefore, an absolute list containing all impacted products is not possible. The SKUs shared are suggested based upon their historical correlation with common *Standard Intermediate Box* labels, which would be impacted. Customers should reference the attached excel file solely as a guide of possible impact, not guaranteed impact. Finally, while Intel will apply these label changes to all product shipments both Engineering Samples and those which have reached a Post Release Qualification (PRQ) status, the attached list only contains SKUs that have reached PRQ, with the exception of Field-Programmable Gate Array (FPGA) products.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 01, 2023	00	Originally Published PCN
April 15, 2024	01	Refreshed list of possible SKUs impacted and added information and disclaimers of change



Product Change Notification

813836-01

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com